PHYSICO-CHEMICAL CHARACTERISTICS OF MILLET BASED COMPOSITE FLOUR

Vandana Choubey¹, S. Patel² and S. Uprit³

BRSM College of Agricultural Engineering and Technology, Mungeli, IGKV Raipur¹, (APFE), Faculty of Agricultural Engineering, IGKV Raipur² College of Dairy Science and Food Technology, Raipur³ Email-choubey.vandana222@gmail.com

Abstract: *Ragi* is considered to be ideal food for diabetic individuals due to its low sugar content. A composite flour utilizing *ragi* and wheat flour is is used to prepare composite flour ratio being 70:30 (Wheat: Finger millet). The composite flour contains fairly good amount protein (10.49%), ash (1.38%) and 251.724 (mg/ 100 g) calcium which shows that the product is nutritionally rich especially in terms of calcium and protein. The fat content (1.5%) is quite low. Therefore, it is also a low fat food which is also good for the peoples suffering from the obesity. For good human health the requirement of calcium and protein is 16:1 (mg: g). The calcium and protein ratio of the developed product is 23.99:1 which is quite higher than the recommended value and also its calcium contain is 251.724 mg/ 100 g. Therefore, it can be able to protect human body from calcium deficiency.

Keywords: Composite flour, ragi, physico-chemical characteristics

REFERENCES

AOAC, (1995). Official Methods of Analysis 16th Edn. J. Assoc. Anal Chem. **37**: 1-10.

Awasthi, P. and Mishra, A. (2004). Dietary constituents: Tips for dietary treatment. *Indian Farmer's Digest.* 28 (9): 43-44

Lakshami kumari, P. and Sumathi, S. (2002). Effect of consumption of finger millet on hyperglycemia in non-insulin dependent diabetes mellitus (NIDDM) subjects. *Plant foods for Human Nutrition*. **57**(3-4):65-69.

Popkin,B.M.;Horton S.;Kims S.;Mahal A. and Shuigao J.(2001). *Nutrition Review*, **59**:379-90.

Regina A.; Bird A.R.; Li Z.; Rahman S.; Mann G.; Chanliaud E.; Berbezy P.; Topping D. and Morell M.K. (2007). *Cereal Foods World*, 52(4), 182-187.53(1), 47-56.

Sindhi R. and Jain S. (2006). Journal of Food Science and Technology, **43**(2), 148-150.